

## HEATING DEVICE AND SEMICONDUCTOR PROCESSING APPARATUS

### ABSTRACT

The present disclosure discloses a heating device and a semiconductor processing apparatus. The disclosed heating device is configured to carry and heat a to-be-processed workpiece in the semiconductor processing apparatus. The heating device includes a base, a heating assembly, and a cooling mechanism. The heating assembly is provided with a ventilation structure. The ventilation structure is configured to blow gas to an edge of the to-be-processed workpiece. The base is arranged on a side of the heating assembly away from a heating surface of the heating assembly. The base and the heating assembly form a mounting space between each other. The cooling mechanism is arranged in the mounting space, located at a position corresponding to an edge area of the heating surface, and configured to cool the heating assembly. The above solution can solve the problem that the uniformity of the film formation of the wafer is poor.

Fig. 2